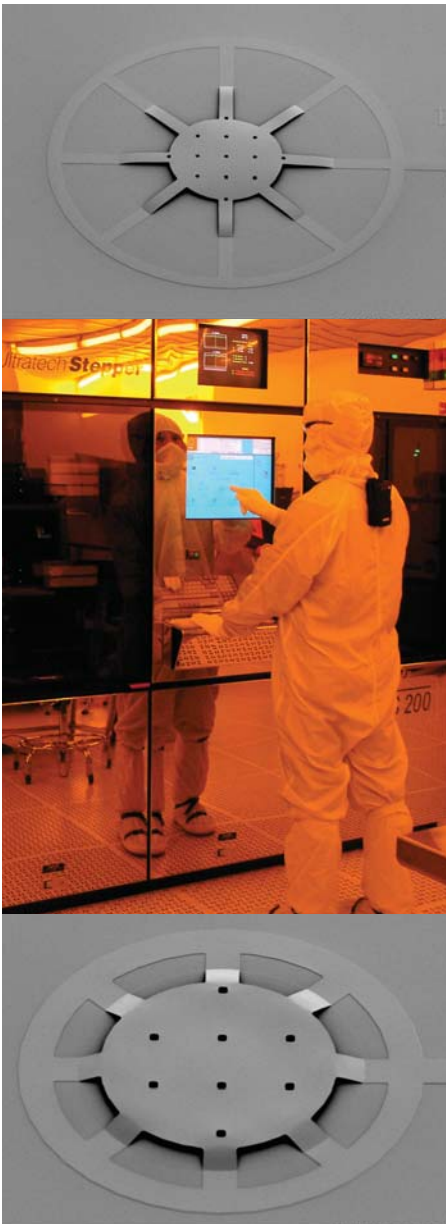


**Quick Facts:**

50,000 ft<sup>2</sup> of certified clean space ♦ 150mm wafer lines ♦ High flexibility in project size ♦ Wide variety of wafer substrates (silicon, SOI, quartz, glass, metal, polyimides.) ♦ Vertically integrated design/fabrication/packaging teams maximize device performance ♦ Skilled support for process transfers/integration where required ♦ In-house metrology and packaging ♦ Scalable custom processes



**Lithography**

**Ultratech 4:1 Reduction Stepper**

.5um Resolution

**Ultratech 1X Stepper**

Backside Alignment Capability  
2um resolution

**Karl SUSS Contact Aligner**

with Backside Alignment Capability

**TEL Track Mark VII and SVG Track**

Positive Photoresist from .65um to 25um  
Negative Photoresist for Patterning & Lift-off  
Specialty Films up to 100um  
SU8, Polyimides, BCB, Barc & CEM films available

**Chemical Vapor Deposition**

**Bruce Technologies BDF-200**

**Atmospheric**

Thermal Oxidation  
POCl<sub>3</sub> Doping

**LPCVD**

Silicon Nitride  
Polysilicon  
TEOS

**JST Wet Benches and SEMI SRDs**

RCA1, RCA2, HF

**STS PECVD**

SiO<sub>2</sub>, SiN, Oxynitride, Amorphous silico

**Wet Processing**

**JST Wet Benches and SEMI SRDs**

HF, 6:1 BOE, Hot Phosphoric, KOH, PAN  
Etch, Lift-off

**Plasma Etching**

**STS ASE DRIE**

**STS Pegasus DRIE**

**LAM 9400**

Silicon, Polysilico, Polyimide

**LAM 9600**

Al, AlSiCu, AlSi, Ti, W, TiO<sub>2</sub>, SiO<sub>2</sub>, HfO<sub>2</sub>,  
Cr, Mo, AlN

**LAM 4520**

SiN, SiO<sub>2</sub>

**LAM DSIE (Q3 2009)**

**Physical Vapor Deposition**

**Sputter – Veeco Connexion Cluster**

Ti, TiW, Ta, Mo, ITO, Al, Al/Si, Al/Si/Cu,  
Al/Nd, SiO<sub>2</sub>, Al<sub>2</sub>O<sub>3</sub>, AlN

**E-beam Metals Evaporation – Temescal**

Cr, Au, Mo, Al, Ni, Sn, Pt, Ti, Ag

**Evaporated Optical Coatings – Leybold 1104 APS**

SiO<sub>2</sub>, HfO<sub>2</sub>, Ta<sub>2</sub>O<sub>5</sub>, TiO<sub>2</sub>

**Resist Strip**

**Ulvac and LAM Microwave O<sub>2</sub> Plasma**

**Piranha**

**EKC 265**

**Sacrificial Releases**

**Xactix XeF<sub>2</sub>**

**Primaxx HF Vapor**

**Ulvac O<sub>2</sub> Polymer Release**

**CMP/Grind**

**CMP – Strasbaugh 6EC**

Polysilicon, SiO<sub>2</sub>, Si Smoothing

**Strasbaugh nGenuity 7AII**

Wafer Grinding

**ITC Value:**

Technical depth ♦ Production Focus ♦ Collaborative Approach ♦ Scalable Solutions  
ITC combines experience and expertise with excellence in producing prototype/low-volume MEMS. We offer the largest array of world-class MEMS-related services in the industry, all under one roof. Visit us at [itcmems.com](http://itcmems.com) or call about your custom MEMS requirements at **(585) 919-3000**.